

International Conference on Changing Landscape in the Semiconductor Packaging World Science Conferences

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Dec 12-13, 2022

Madeira, Portugal

IMPORTANT DATES:

Paper Submission: Sept 19, 2022	Acceptance Notification: Oct 10, 2022	Final Manuscript Due: Nov 18, 2022
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TOPICS:

Authors are invited to submit their original papers to address the topics of the conference, including but not limited to:

HETEROGENEOUS INTEGRATION (HI)	ADVANCED PACKAGING ROADMAP AND MARKET UPDATES	PACKAGING TECHNOLOGY & PROCESSES
PACKAGE SIMULATION, EVALUATION & CHARACTERIZATION <ul style="list-style-type: none"> Heterogeneous Integration Test Impacts 3D Bump Metrology and Inspection Intelligent Infrastructure and Guidance Systems Intertwined development of manufacturing processes and test technologies – a prerequisite for future success in advanced packaging Virtual Prototyping for System-in-Package with Heterogeneous Integration 	<ul style="list-style-type: none"> The Growing Momentum of Heterogeneous Integration Challenges for Heterogeneous Integration in Package – Applications Driving Materials and Processes towards Diversity Micro Balling on Chips with a High Ball-count for Space Applications Big Data and Vehicle Analytics Vehicular Networks Security and Safety 	<ul style="list-style-type: none"> Active Mold Packaging for Novel Antenna-in-Package Interconnection and Manufacturing High Throughput & High Yield Heterogeneous Integration with Implemented Metrology for Collective D2W Bonding High Throughput & High Yield Heterogeneous Integration with Implemented Metrology for Collective D2W Bonding
CASE STUDIES OF ENABLING DIGITALIZATION IN KEY INDUSTRIES WITH ADVANCED PACKAGING SOLUTIONS	UPDATES IN MANUFACTURING EQUIPMENT WITH ADVANCED CAPABILITIES	WAFER MANUFACTURING TECHNOLOGIES
DESIGN FOR RELIABILITY AND PERFORMANCE	<ul style="list-style-type: none"> Processing of new functional materials Manufacturing process IP 	<ul style="list-style-type: none"> How can ADK (Assembly Design Kits) be developed and linked to PDK (Process Design Kits) of chip design Wafer manufacturing technologies

OUTSTANDING PAPERS:

Based on the peer review scores as well as the presentations at the conference, the authors of outstanding papers will be invited to extend their works for a potential publication in journals special issues with high impact factors.

PAPER SUBMISSION:

For more information, please refer to the conference website: <https://wsconf.org/Conference/CLSP>

CONTACT

For more information, please send an email to clsp@wsconf.org

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